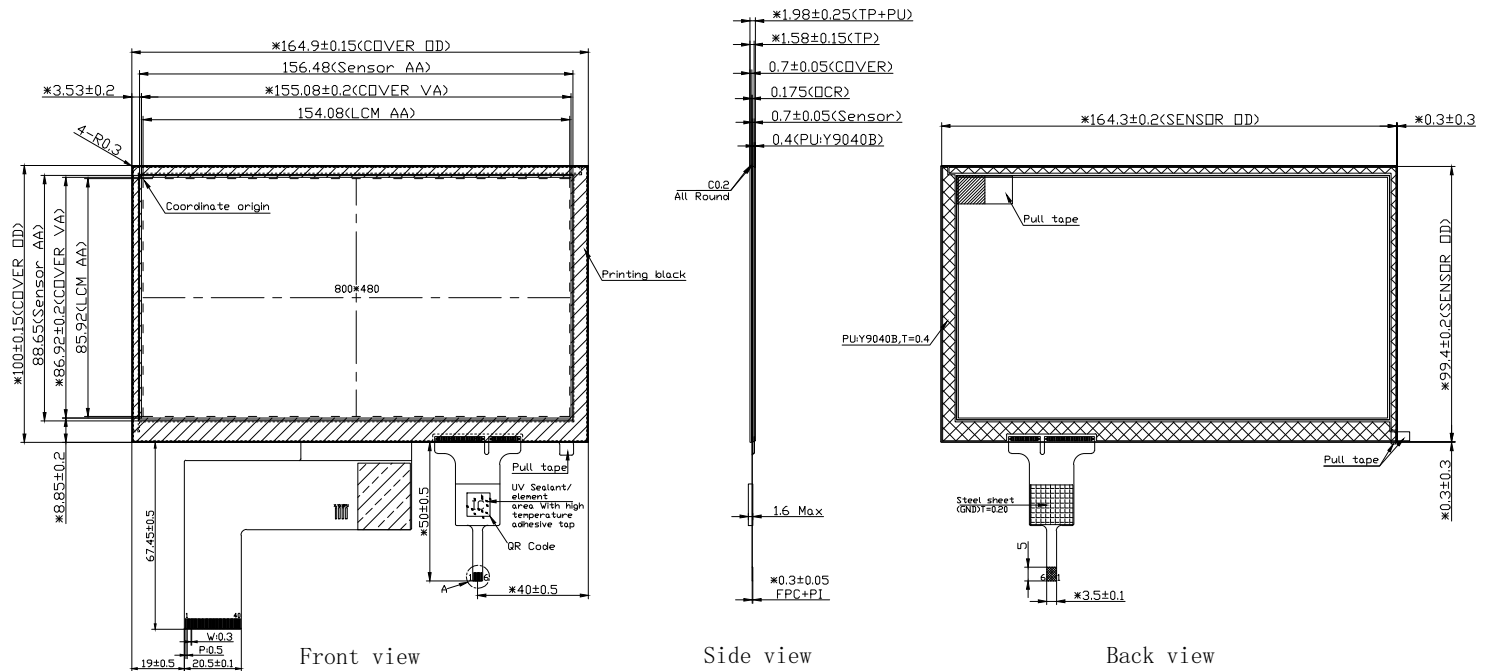


TECHNOLOGY CHARACTERISTICS CTP

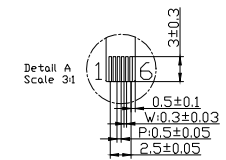
PROPERTY	Requirement
STRCUTURE	G+G
Bonding Type	/
TOUCH IC	GT911
NO. OF TOUCH	5
Cover glass Thickness	0.7mm(Sodalime)
ITO Glass Thickness	0.7mm
Surface Hardness	≥6H
Light Transmittance	85% Min
Operating Temperature	-10~50° C
Storage Temperature	-20~60° C

THE DRAWING ON THIS PRINT AND INFORMATION THEREWITH ARE PROPRIETARY TO FANNAL AND SHALL NOT BE USED IN WHOLE OR IN PART WITHOUT WRITTEN PERMISSION OF FANNAL.



NOTES:  
 \*:Important dimensions  
 TOLERANCE UNLESS:x.x±0.3  
 OTHERWISE SPECIFIED:x.xx±0.2  
 DIMENSIONS IN MM:ANGULAR:±1°

Pin No.	Definition
1	VDD(3.3V)
2	GND
3	INT(3.3V)
4	SDA(3.3V)
5	SCL(3.3V)
6	RST(3.3V)



**RoHS**

					DRAWN	Yan	TITLE	Drawing NO:CT0476-V1.0
					CHECKED	Lee	MODULE SPEC.	Product NO:FN070AM133-V1.0
					APPROVED	Dolphe		Project No: TPM8469
					CSR APPROVED			
					Customer No:			
1.0	First issue		Yan	2019.12.05	3rd Angle			
VER.	SYMBOL	AMENDMENT	SIGN	DATE	SHEET 1 OF 1			

**FANNAL ELECTRONICS CO., LTD**